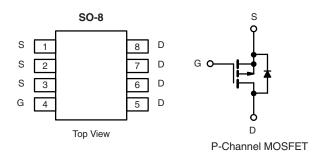


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Vishay Siliconix

# Automotive P-Channel 30 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	- 30				
$R_{DS(on)}(\Omega)$ at $V_{GS} = -10 \text{ V}$	0.012				
$R_{DS(on)}(\Omega)$ at $V_{GS} = -4.5 \text{ V}$	0.019				
I <sub>D</sub> (A)	- 18				
Configuration	Single				



#### **FEATURES**

- TrenchFET® Power MOSFET
- AEC-Q101 Qualified<sup>c</sup>
- 100 % R<sub>a</sub> and UIS Tested
- Material categorization:
   For definitions of compliance please see www.vishay.com/doc?99912





ROHS COMPLIANT HALOGEN FREE

ORDERING INFORMATION				
Package	SO-8			
Lead (Pb)-free and Halogen-free	SQ4425EY-T1-GE3			

<b>ABSOLUTE MAXIMUM RATING</b>	S (T <sub>C</sub> = 25 °C, unles	s otherwise noted	(b)		
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		$V_{DS}$	- 30		
Gate-Source Voltage		V <sub>GS</sub>	± 20	V	
Continuous Drain Current	T <sub>C</sub> = 25 °C	1	- 18		
	T <sub>C</sub> = 125 °C	- I <sub>D</sub>	- 10		
Continuous Source Current (Diode Conduction)		I <sub>S</sub>	- 6	А	
Pulsed Drain Current <sup>a</sup>		I <sub>DM</sub>	- 70		
Single Pulse Avalanche Current		I <sub>AS</sub>	- 38		
Single Pulse Avalanche Energy	L = 0.1 mH	E <sub>AS</sub>	72	mJ	
Maximum Power Dissipation <sup>a</sup>	T <sub>C</sub> = 25 °C	D	6.8	W	
	T <sub>C</sub> = 125 °C	- P <sub>D</sub>	2.2		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 175	°C	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount <sup>b</sup>	$R_{thJA}$	85	°C/W
Junction-to-Foot (Drain)		$R_{thJF}$	22	C/ VV

## Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. When mounted on 1" square PCB (FR-4 material).
- c. Parametric verification ongoing.



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PARAMETER	SYMBOL	TES	MIN.	TYP.	MAX.	UNIT	
Static						l .	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$		- 30		=-	V
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$		- 2.0	- 2.5	V
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> =	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	± 100	nA
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = - 30 V	-	-	- 1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = - 30 V, T <sub>J</sub> = 125 °C	-	-	- 50	μΑ
		V <sub>GS</sub> = 0 V	V <sub>DS</sub> = - 30 V, T <sub>J</sub> = 175 °C	-	-	- 150	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = - 10 V	$V_{DS} \le -5 V$	- 30	-	-	Α
		V <sub>GS</sub> = - 10 V	I <sub>D</sub> = - 13 A	-	0.009	0.012	
Dunin Course On Otata Basistanas		V <sub>GS</sub> = - 10 V	I <sub>D</sub> = - 13 A, T <sub>J</sub> = 125 °C	-	-	0.018	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = - 10 V	I <sub>D</sub> = - 13 A, T <sub>J</sub> = 175 °C	-	-	0.021	Ω
		V <sub>GS</sub> = - 4.5 V	I <sub>D</sub> = - 10 A	-	0.015	0.019	
Forward Transconductanceb	9 <sub>fs</sub>	V <sub>DS</sub> =	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 13 A		35	-	S
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			-	2900	3630	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$	V <sub>DS</sub> = - 25 V, f = 1 MHz	-	527	660	pF
Reverse Transfer Capacitance	C <sub>rss</sub>			-	418	525	
Total Gate Charge <sup>c</sup>	Qg			-	33.6	50	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>GS</sub> = - 4.5 V	V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 11 A	-	8.6	-	nC
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			-	15.2	-	
Gate Resistance	$R_g$		f = 1 MHz		2.04	4	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			-	12	18	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD}$ = - 15 V, $R_L$ = 15 $\Omega$ $I_D \cong$ - 1 A, $V_{GEN}$ = - 10 V, $R_g$ = 1 $\Omega$		-	9	14	- ns
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	54	81	
Fall Time <sup>c</sup>	t <sub>f</sub>			-	13	20	
Source-Drain Diode Ratings and Char-	acteristics <sup>b</sup>	•					
Pulsed Current <sup>a</sup>	I <sub>SM</sub>				-	- 70	Α
Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> =	I <sub>F</sub> = - 10 A, V <sub>GS</sub> = 0 V		- 0.82	- 1.2	V

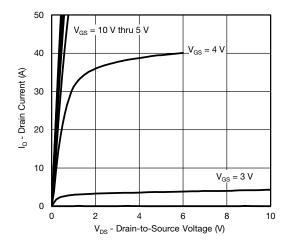
## Notes

- a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

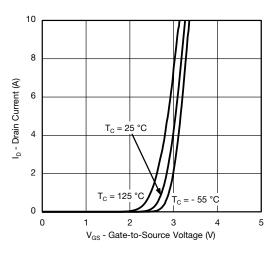
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



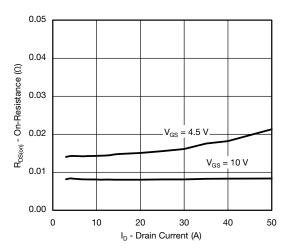
# TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)



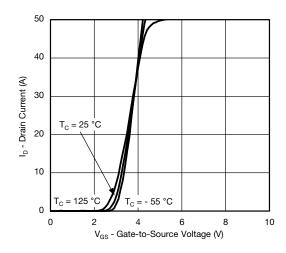
#### **Output Characteristics**



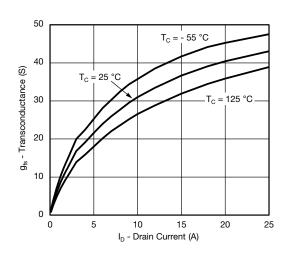
### **Transfer Characteristics**



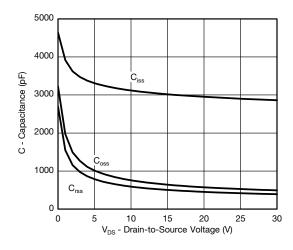
On-Resistance vs. Drain Current



#### **Transfer Characteristics**



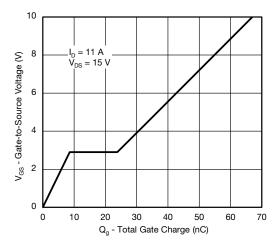
### Transconductance



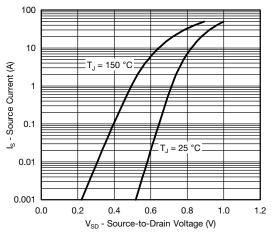
Capacitance



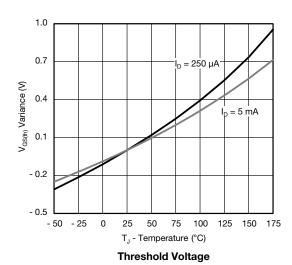
# TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)



#### **Gate Charge**

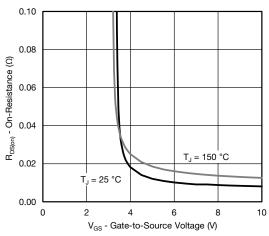


**Source Drain Diode Forward Voltage** 

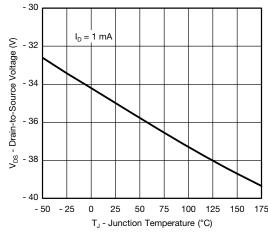


1.9  $I_{D} = 11 A$ R<sub>DS(on)</sub> - On-Resistance (Normalized) 1.7  $V_{GS} = 10 \text{ V}$ 1.5 1.3 1.1 0.9 0.7 0.5 - 25 150 175 - 50 0 25 50 75 100 125 T<sub>.</sub>I - Junction Temperature (°C)

On-Resistance vs. Junction Temperature

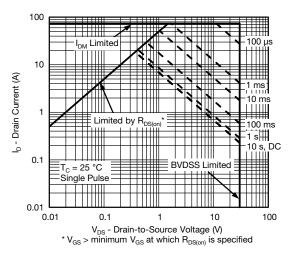


On-Resistance vs. Gate-to-Source Voltage

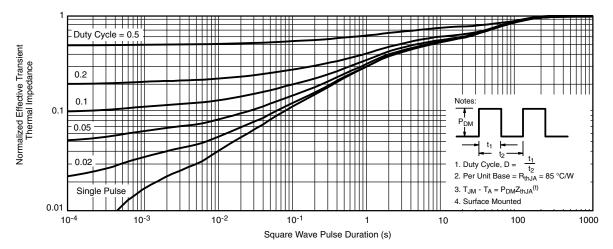


**Drain Source Breakdown vs. Junction Temperature** 

# **THERMAL RATINGS** ( $T_A = 25$ °C, unless otherwise noted)



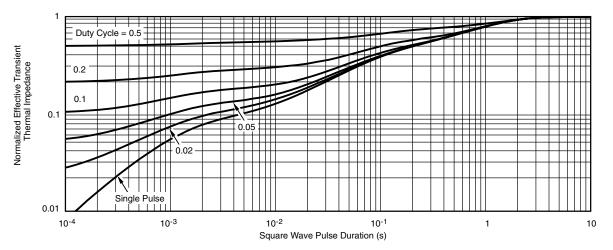
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



# THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

- The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

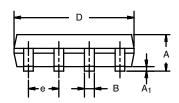
are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

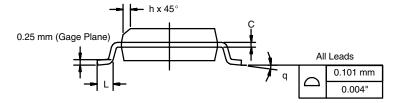
Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?72179">www.vishay.com/ppg?72179</a>.



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIM	IETERS	INC	HES	
DIM	Min	Max	Min	Max	
Α	1.35	1.75	0.053	0.069	
A <sub>1</sub>	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
Е	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I. 11-Sep-06					

DWG: 5498

Document Number: 71192 www.vishay.com 11-Sep-06

# APPLICATION NOTE



## **RECOMMENDED MINIMUM PADS FOR SO-8**



Recommended Minimum Pads Dimensions in Inches/(mm)

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